Part Number	AS4C16M32MD1-5BCN / AS4C16M32MD1-5BIN						
Part Weight	144.4mg						
Material	**Substances**	**Vendor**	**Type**	**CAS No.**	**Weight**	**%**	**PPM**
Silicon Chip	Silicon (Si)	JSC	512M DDR_x32		3.300	2.29%	22853
Encapsulation (Mold Compound)	Silica, vitreous	KCC	KTMC-5900GPU	60676-86-0	66.848	46.29%	462935
	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethyl(1,1'-biphenyl)			85954-11-6	2.332	1.61%	16149
	Phenol, Polymer with 1,4 -bis benzene			26834-02-6	2.332	1.61%	16149
	Carbon Black			1333-86-4	0.466	0.32%	3230
	Others			Trade secret	5.752	3.98%	39834
Substrate	Continuous Filament Fiber Glass	MTG	SU-FBJS-09001W H	65997-17-3	4.983	3.45%	34508
	Copper			7440-50-8	14.949	10.35%	103523
	Bismaleimide / Triazine			13676-54-5/25722-66	12.074	8.36%	83615
	Epoxy Resin			26265-08-7	4.216	2.92%	29199
	Inorganic filler			13776-74-4/7631-86-9	0.767	0.53%	5309
	Morpholine derivative(solder resist)			Trade secret	0.767	0.53%	5309
	Nickel			7440-02-0	0.460	0.32%	3185
	Gold			13967-50-5	0.115	0.08%	796
Die Attach (Adhesive)	Acrylic Epoxy Adhesive	KCC	WA-330H-20T	Trade secret	0.546	0.38%	3781
	Acrylic Pressure Sensitive Adhesive			Trade secret	0.294	0.20%	2036
Gold Wire	Gold (Au)	Heesiung	0.8mil Au wire	7440-57-5	0.640	0.44%	4432
	Beryllium			7440-41-7	0.000	0.00%	0
	Others			Trade secret	0.000	0.00%	0
Solder Ball	Tin	Duksan	0.35mm (Sn/1.2Ag/0.5Cu/0.05Ni)	7440-31-5	23.148	16.03%	160303
	Silver			7440-22-4	0.283	0.20%	1958
	Copper			7440-50-8	0.118	0.08%	816
	Nickel			7440-02-0	0.012	0.01%	82
						100.00%	